

阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描述上的差异，建议读者做出适当判断。
- 4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

Read Statement

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .

The MC100ES6011 is a differential 1:2 fanout buffer. The ES6011 is ideal for applications requiring lower voltage.

The 100ES Series contains temperature compensation.

Features

- 270 ps Typical Propagation Delay
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range: $V_{CC} = 2.375\text{ V}$ to 3.8 V with $V_{EE} = 0\text{ V}$
- ECL Mode Operating Range: $V_{CC} = 0\text{ V}$ with $V_{EE} = -2.375\text{ V}$ to -3.8 V
- Open Input Default State
- Q Output Will Default LOW with Inputs Open or at V_{EE}
- LVDS Input Compatible
- 8-Lead SOIC and TSSOP Pb-Free Packages Available

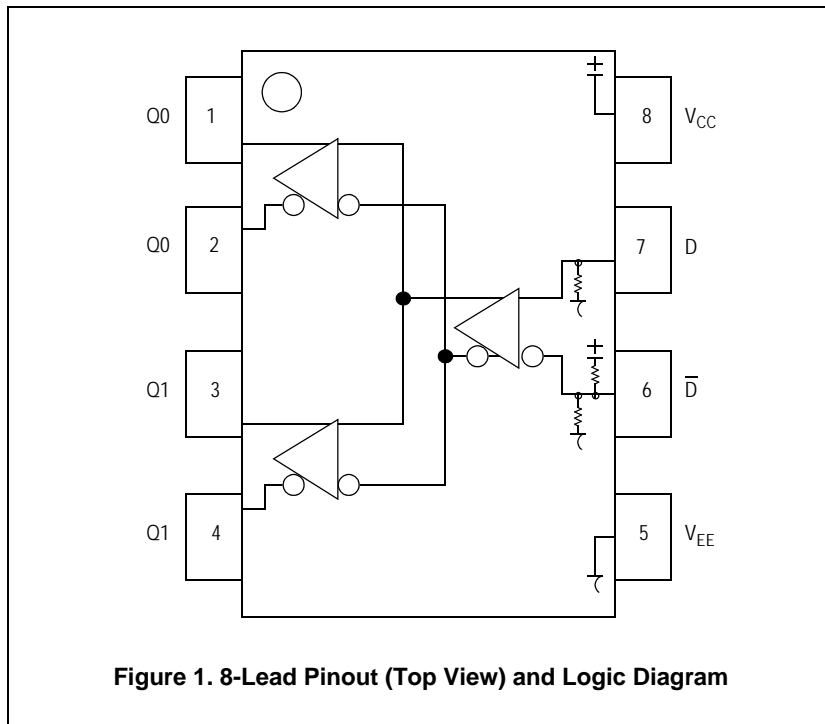


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

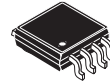
MC100ES6011



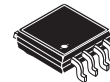
D SUFFIX
8-LEAD SOIC PACKAGE
CASE 751-07



EF SUFFIX
8-LEAD SOIC PACKAGE
Pb-FREE PACKAGE
CASE 751-07



DT SUFFIX
8-LEAD TSSOP PACKAGE
CASE 1640-01



EJ SUFFIX
8-LEAD TSSOP PACKAGE
Pb-FREE PACKAGE
CASE 1640-01

ORDERING INFORMATION

Device	Package
MC100ES6011D	SO-8
MC100ES6011DR2	SO-8
MC100ES6011EF	SO-8 (Pb-Free)
MC100ES6011EFR2	SO-8 (Pb-Free)
MC100ES6011DT	TSSOP-8
MC100ES6011DTR2	TSSOP-8
MC100ES6011EJ	TSSOP-8 (Pb-Free)
MC100ES6011EJR2	TSSOP-8 (Pb-Free)

PIN DESCRIPTION

Pin	Function
D ⁽¹⁾ , D ⁽²⁾	ECL Data Inputs
Q0, Q0, Q1, Q1	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply

1. Pins will default LOW when left open.
2. Pins will default to $0.572 V_{CC}/2$ when left open.

Table 1. Attributes

Characteristics		Value
Internal Input Pulldown Resistor		75 k Ω
Internal Input Pullup Resistor		56 k Ω
ESD Protection	Human Body Model Machine Model Charged Device Model	> 4000 V > 200 V > 1500 V
θ_{JA} Thermal Resistance (Junction to Ambient)	0 LFPM, 8 SOIC 500 LFPM, 8 SOIC	190°C/W 130°C/W

Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test

Table 2. Maximum Ratings⁽¹⁾

Symbol	Parameter	Conditions	Rating	Units
V_{SUPPLY}	Power Supply Voltage	Difference between V_{CC} & V_{EE}	3.9	V
V_{IN}	Input Voltage	$V_{CC}-V_{EE} < 3.6$ V	$V_{CC}+0.3$ $V_{EE}-0.3$	V V
I_{OUT}	Output Current	Continuous Surge	50 100	mA mA
TA	Operating Temperature Range		-40 to +85	°C
T_{stg}	Storage Temperature Range		-65 to +150	°C

1. Absolute maximum continuous ratings are those maximum values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation at absolute-maximum-rated conditions is not implied.

Table 3. DC Characteristics ($V_{CC} = 0$ V; $V_{EE} = -2.5$ V \pm 5% or $V_{CC} = 2.5$ V \pm 5%; $V_{EE} = 0$ V)⁽¹⁾

Symbol	Characteristic	-40°C			0°C to 85°C			Unit
		Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		12	25		12	25	mA
V_{OH}	Output HIGH Voltage ⁽²⁾	$V_{CC}-1135$		$V_{CC}-760$	$V_{CC}-1070$		$V_{CC}-760$	mV
V_{OL}	Output LOW Voltage ⁽²⁾	$V_{CC}-1950$		$V_{CC}-1350$	$V_{CC}-1950$		$V_{CC}-1520$	mV
V_{OUTPP}	Output Peak-to-Peak Voltage	200			200			mV
V_{IH}	Input HIGH Voltage (Single Ended)	$V_{CC}-1165$		$V_{CC}-880$	$V_{CC}-1165$		$V_{CC}-880$	mV
V_{IL}	Input LOW Voltage (Single Ended)	$V_{CC}-1810$		$V_{CC}-1475$	$V_{CC}-1810$		$V_{CC}-1475$	mV
V_{PP}	Differential Input Voltage ⁽³⁾	0.12		1.3	0.12		1.3	V
V_{CMR}	Differential Cross Point Voltage ⁽⁴⁾	$V_{EE}+1.0$		$V_{CC}-0.8$	$V_{EE}+1.0$		$V_{CC}-0.8$	V
I_{IN}	Input Current			± 150			± 150	μ A

- ES6011 circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow > 500 LFPM is maintained.
- Output termination voltage $V_{TT} = 0$ V for $V_{CC} = 2.5$ V operation is supported but the power consumption of the device will increase.
- V_{PP} (DC) is the minimum differential input voltage swing required to maintain device functionality.
- V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} (DC) range and the input swing lies within the V_{PP} (DC) specification.

Table 4. DC Characteristics ($V_{CC} = 0\text{ V}$; $V_{EE} = -3.8\text{ to }-3.135\text{ or }V_{CC} = 3.8\text{ to }3.135\text{ V}$; $V_{EE} = 0\text{ V}$)⁽¹⁾

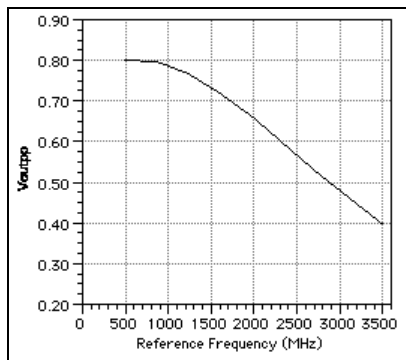
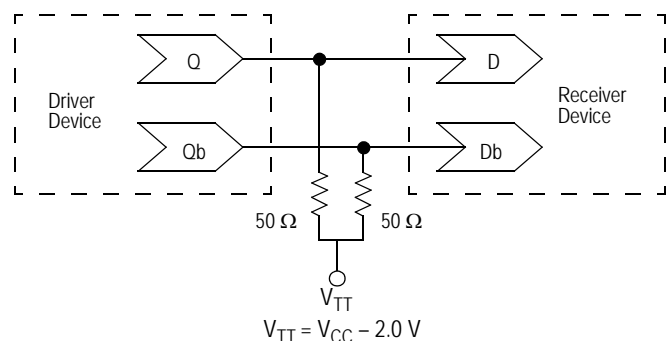
Symbol	Characteristic	-40°C			0°C to 85°C			Unit
		Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		12	25		12	25	mA
V_{OH}	Output HIGH Voltage ⁽²⁾	$V_{CC} - 1135$		$V_{CC} - 760$	$V_{CC} - 1070$		$V_{CC} - 760$	mV
V_{OL}	Output LOW Voltage ⁽²⁾	$V_{CC} - 1950$		$V_{CC} - 1500$	$V_{CC} - 1950$		$V_{CC} - 1520$	mV
V_{OUTPP}	Output Peak-to-Peak Voltage	200			200			mV
V_{IH}	Input HIGH Voltage (Single Ended)	$V_{CC} - 1165$		$V_{CC} - 880$	$V_{CC} - 1165$		$V_{CC} - 880$	mV
V_{IL}	Input LOW Voltage (Single Ended)	$V_{CC} - 1810$		$V_{CC} - 1475$	$V_{CC} - 1810$		$V_{CC} - 1475$	mV
V_{PP}	Differential Input Voltage ⁽³⁾	0.12		1.3	0.12		1.3	V
V_{CMR}	Differential Cross Point Voltage ⁽⁴⁾	$V_{EE} + 1.0$		$V_{CC} - 0.8$	$V_{EE} + 1.0$		$V_{CC} - 0.8$	V
I_{IN}	Input Current			± 150			± 150	μA

- ES6011 circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow $> 500\text{ LFPM}$ is maintained.
- Output termination voltage $V_{TT} = 0\text{ V}$ for $V_{CC} = 2.5\text{ V}$ operation is supported but the power consumption of the device will increase.
- V_{PP} (DC) is the minimum differential input voltage swing required to maintain device functionality.
- V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} (DC) range and the input swing lies within the V_{PP} (DC) specification.

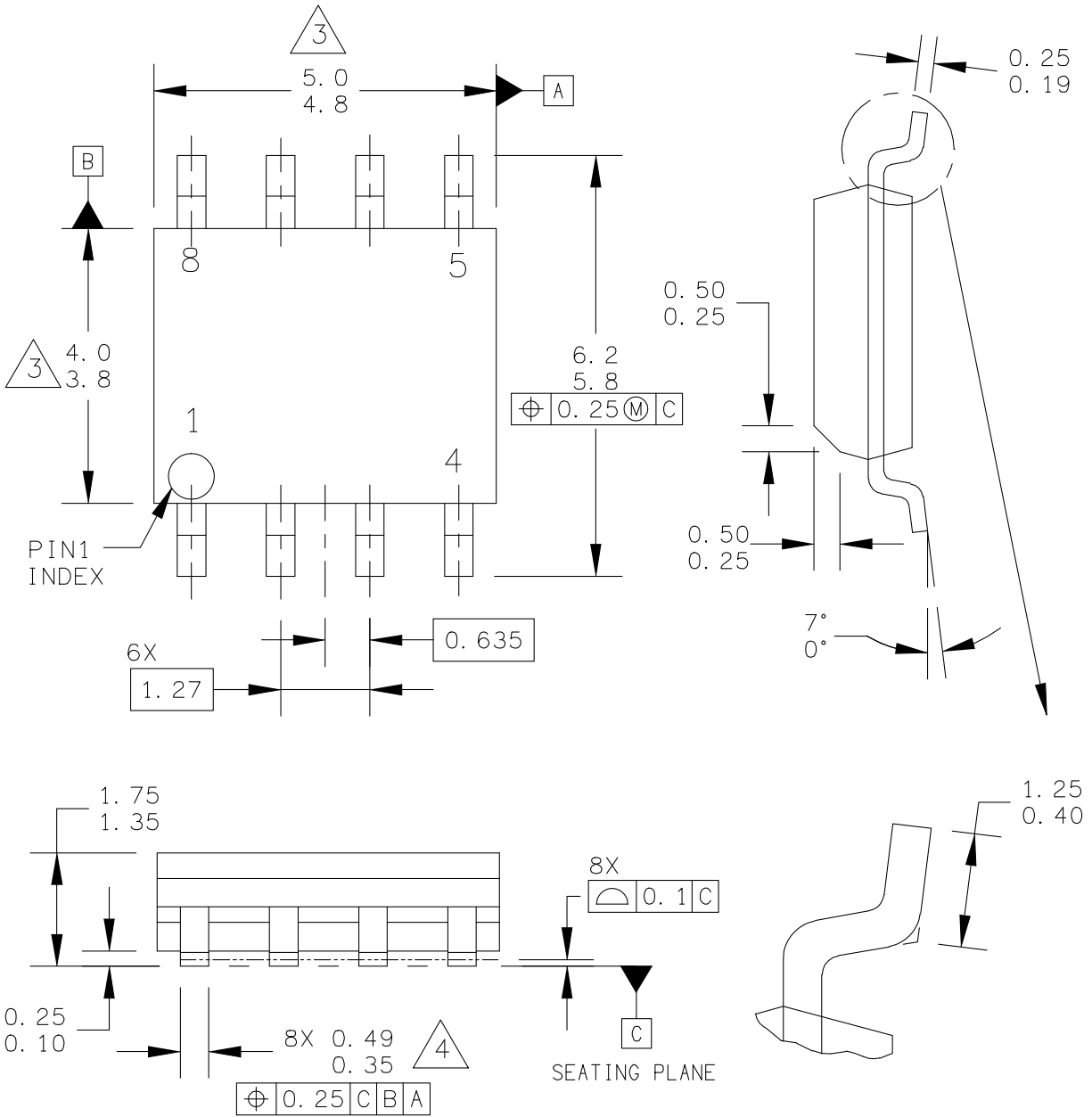
Table 5. AC Characteristics ($V_{CC} = 0\text{ V}$; $V_{EE} = -3.8\text{ to }-2.375\text{ or }V_{CC} = 2.375\text{ to }3.8\text{ V}$; $V_{EE} = 0\text{ V}$)⁽¹⁾

Symbol	Characteristic	-40°C			25°C			0°C to 85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Maximum Frequency		> 3			> 3			> 3		GHz
t_{PLH} , t_{PHL}	Propagation Delay (Differential) CLK to Q, \bar{Q}	170	260	300	180	270	310	210	285	360	ps
t_{SKEW}	Within Device Skew Q, \bar{Q} Device-to-Device Skew ⁽²⁾		9	20 130		9	20 130		9	20 150	ps
t_{JITTER}	Cycle-to-Cycle Jitter RMS (1σ)			1			1			1	ps
V_{PP}	Input Voltage Swing (Differential)	150		1200	150		1200	150		1200	mV
V_{CMR}	Differential Cross Point Voltage	$V_{EE} + 1.2$		$V_{CC} - 1.1$	$V_{EE} + 1.2$		$V_{CC} - 1.1$	$V_{EE} + 1.2$		$V_{CC} - 1.1$	V
t_r , t_f	Output Rise/Fall Times (20% – 80%)	70		220	70		220	70		220	ps

- Measured using a 750 mV source 50% Duty Cycle clock source. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.
- Skew is measured between outputs under identical transitions.

**Figure 2. V_{OUTPP} versus Frequency****Figure 3. Typical Termination for Output Driver and Device Evaluation**

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 8LD SOIC NARROW BODY	DOCUMENT NO: 98ASB42564B	REV: U
	CASE NUMBER: 751-07	07 APR 2005
	STANDARD: JEDEC MS-012AA	

CASE 751-07
ISSUE U
8-LEAD SOIC PACKAGE

PAGE 1 OF 2

PACKAGE DIMENSIONS

NOTES:

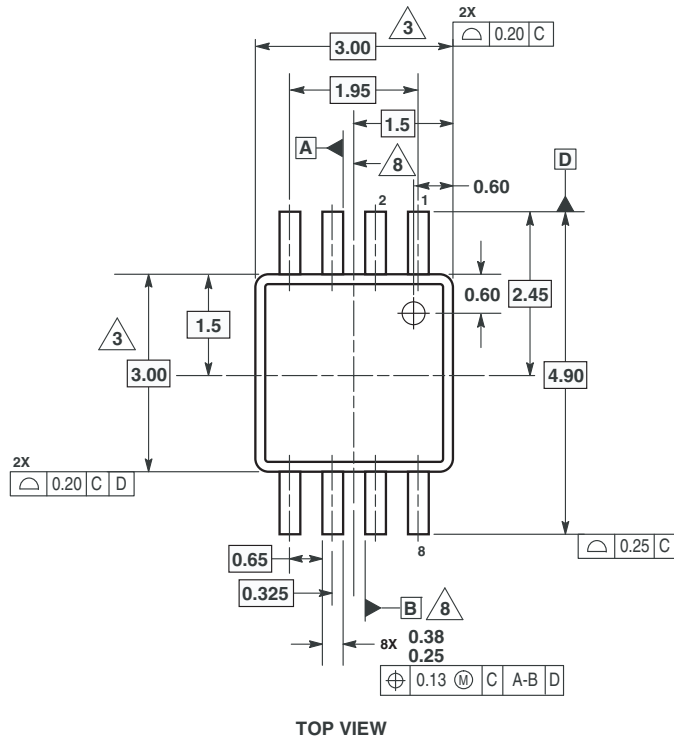
1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 8LD SOIC NARROW BODY	DOCUMENT NO: 98ASB42564B	REV: U	
	CASE NUMBER: 751-07	07 APR 2005	
	STANDARD: JEDEC MS-012AA		

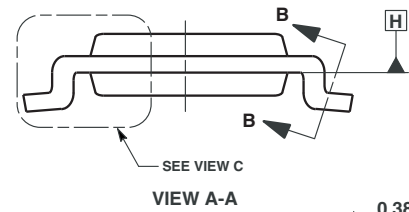
**CASE 751-07
ISSUE U
8-LEAD SOIC PACKAGE**

PAGE 2 OF 2

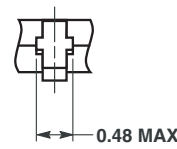
PACKAGE DIMENSIONS



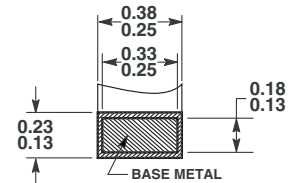
TOP VIEW



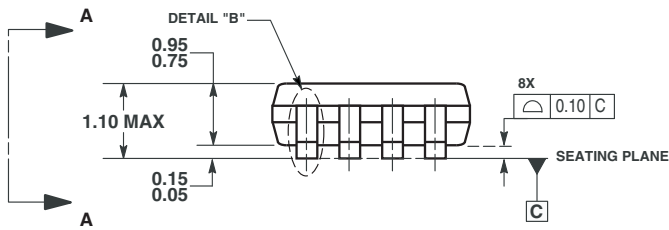
VIEW A-A



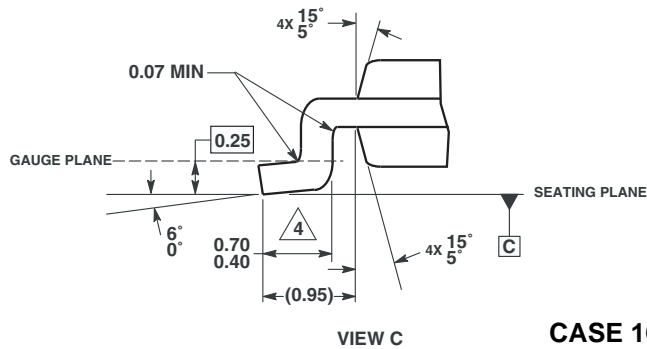
**DETAIL "B"
DAMBAR PROTRUSION**



**SECTION B-B
SEE NOTE 6**



SIDE VIEW



VIEW C

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS ARE IN MILLIMETERS.
3. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT DATUM H, MOLD FLASH OR PROTRUSIONS, SHALL NOT EXCEED 0.15mm PER SIDE.
4. DIMENSION IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
5. THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.14mm SEE DETAIL "B" AND SECTION B-B.
6. SECTION B-B TO BE DETERMINED AT 0.10 TO 0.25mm FROM THE LEAD TIP.
7. THIS PART IS COMPLIANT WITH JEDEC REGISTRATION MO-187 AA.
8. DATUMS A AND B TO BE DETERMINED DATUM PLANE H.

**CASE 1640-01
ISSUE O
8-LEAD TSSOP PACKAGE**

Revision History Sheet

Rev	Table	Page	Description of Change	Date
5		1	Product Discontinuance Notice – Last Time Buy Expires on (12/19/2013)	2/5/2013

We've Got Your Timing Solution



6024 Silver Creek Valley Road
San Jose, California 95138

Sales
800-345-7015 (inside USA)
+408-284-8200 (outside USA)
Fax: 408-284-2775
www.IDT.com/go/contactIDT

Technical Support
netcom@idt.com
+480-763-2056

DISCLAIMER Integrated Device Technology, Inc. (IDT) and its subsidiaries reserve the right to modify the products and/or specifications described herein at any time and at IDT's sole discretion. All information in this document, including descriptions of product features and performance, is subject to change without notice. Performance specifications and the operating parameters of the described products are determined in the independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in applications involving extreme environmental conditions or in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are registered trademarks of IDT. Other trademarks and service marks used herein, including protected names, logos and designs, are the property of IDT or their respective third party owners.

Copyright 2013. All rights reserved.